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(54) Title: SUBSTRATE FOR INTEGRATED CIRCUIT DEVICES INCLUDING MULTI-LAYER GLASS CORE AND METHODS OF MAKING THE SAME

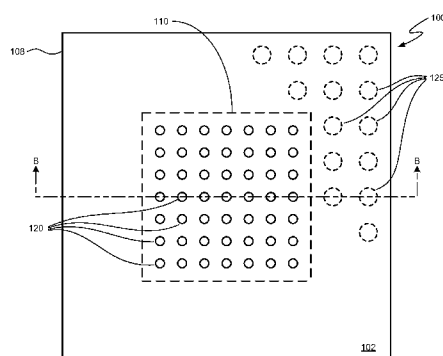


FIG. 1A

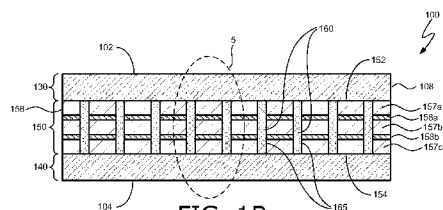


FIG. 1B

(57) Abstract: Disclosed are embodiments of a substrate for an integrated circuit (IC) device. The substrate includes a core comprised of two or more discrete glass layers that have been bonded together. A separate bonding layer may be disposed between adjacent glass layers to couple these layers together. The substrate may also include build-up structures on opposing sides of the multi-layer glass core, or perhaps on one side of the core. Electrically conductive terminals may be formed on both sides of the substrate, and an IC die may be coupled with the terminals on one side of the substrate. The terminals on the opposing side may be coupled with a next-level component, such as a circuit board. One or more conductors extend through the multi-layer glass core, and one or more of the conductors may be electrically coupled with the build-up structures disposed over the core. Other embodiments are described and claimed.